

# SOT1850-1

VFBGA176, plastic, very thin fine-pitch ball grid array; 176 balls; 0.5 mm pitch; 9 mm x 9 mm x 0.86 mm body

30 July 2018

Package information

## 1 Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	VFBGA176
<b>Package style descriptive code</b>	VFBGA (very thin fine-pitch ball grid array)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	13-07-2018
<b>Manufacturer package code</b>	98ASA00942D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	9	-	mm
package width	-	9	-	mm
package height	-	0.86	-	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	176	-	



2 Package outline

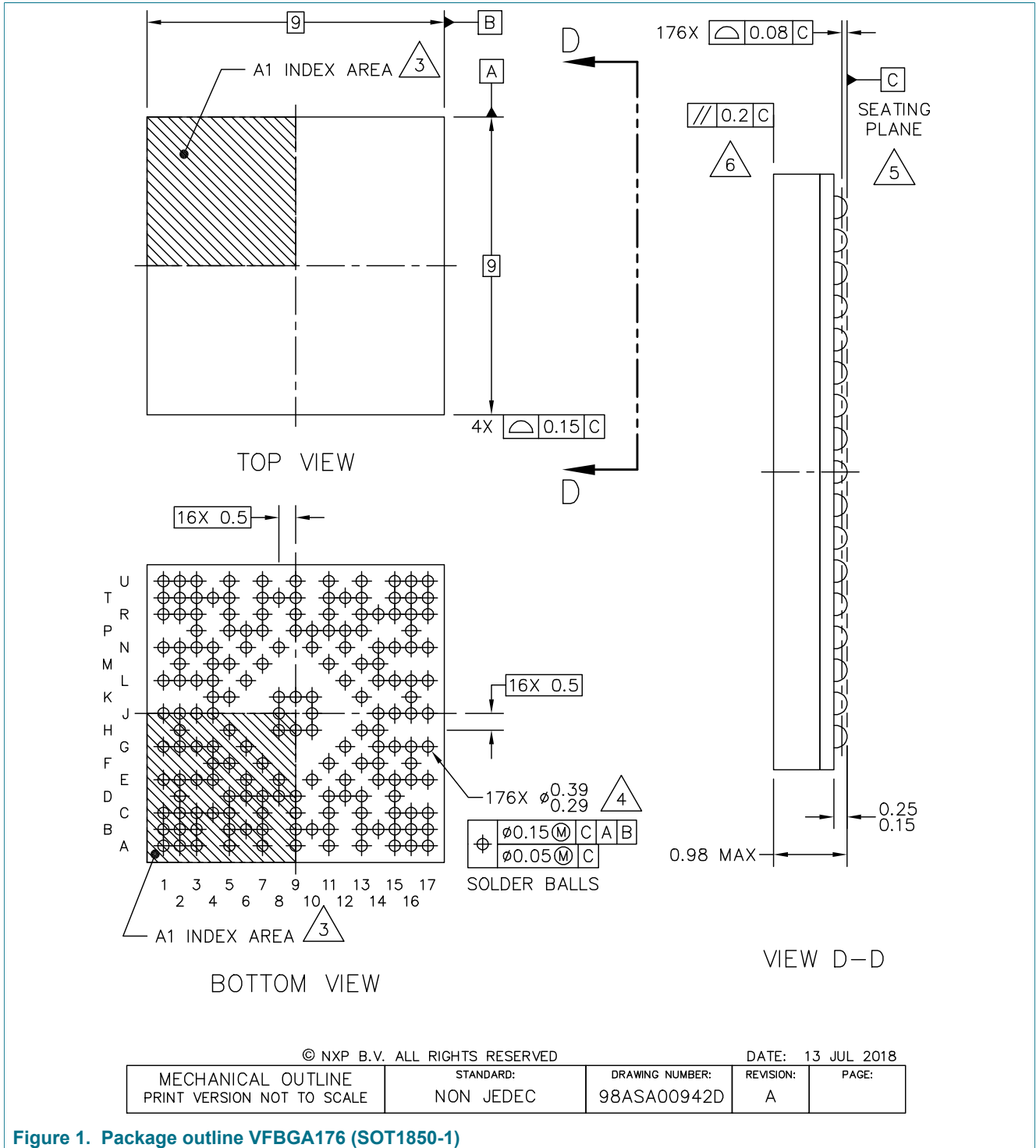


Figure 1. Package outline VFBGA176 (SOT1850-1)

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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DATE: 13 JUL 2018

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA00942D	REVISION: A	PAGE:
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Figure 2. Package outline note VFBGA176 (SOT1850-1)

3 Soldering

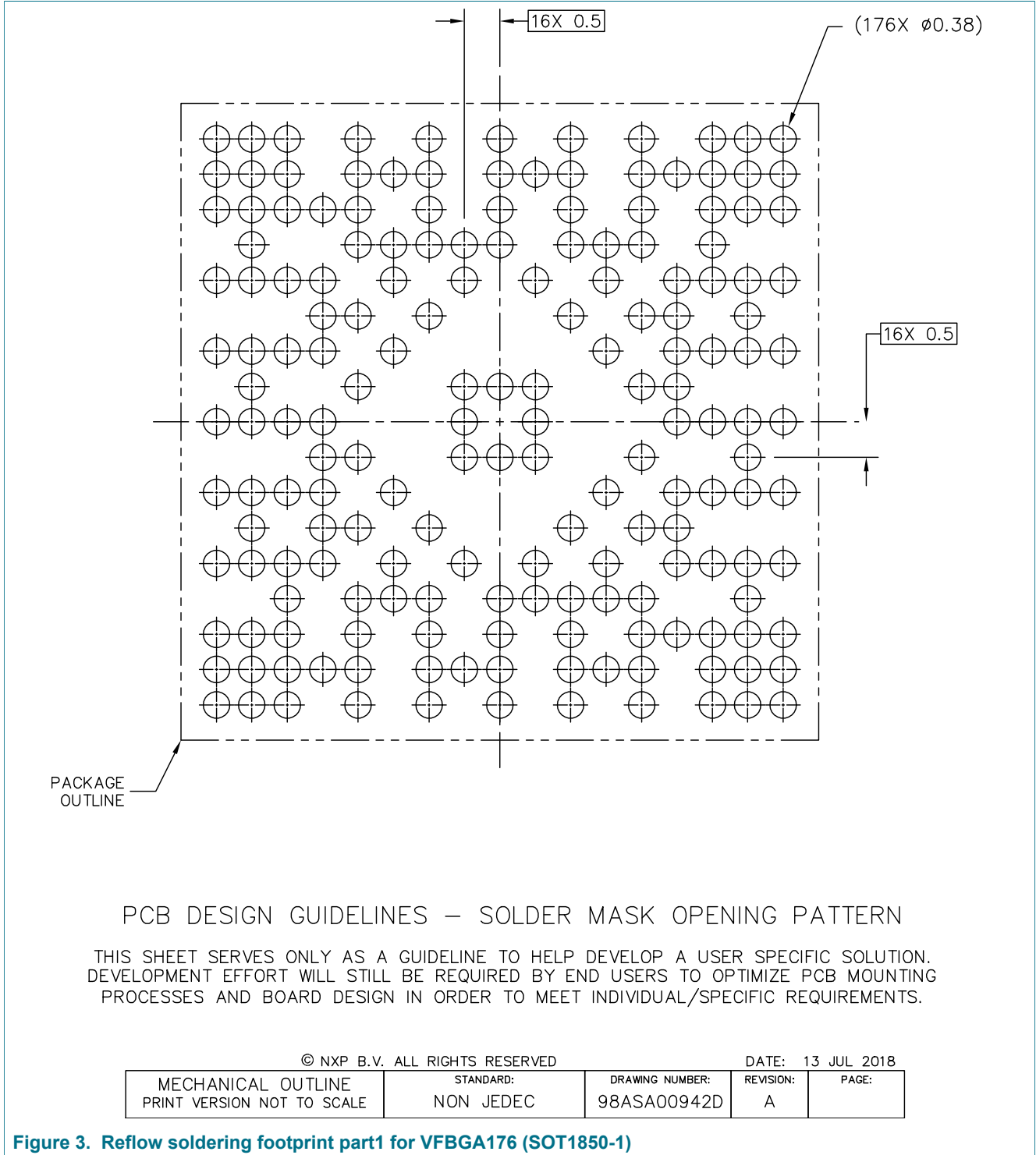


Figure 3. Reflow soldering footprint part1 for VFBGA176 (SOT1850-1)

VFBGA176, plastic, very thin fine-pitch ball grid array; 176 balls; 0.5 mm pitch; 9 mm x 9 mm x 0.86 mm body

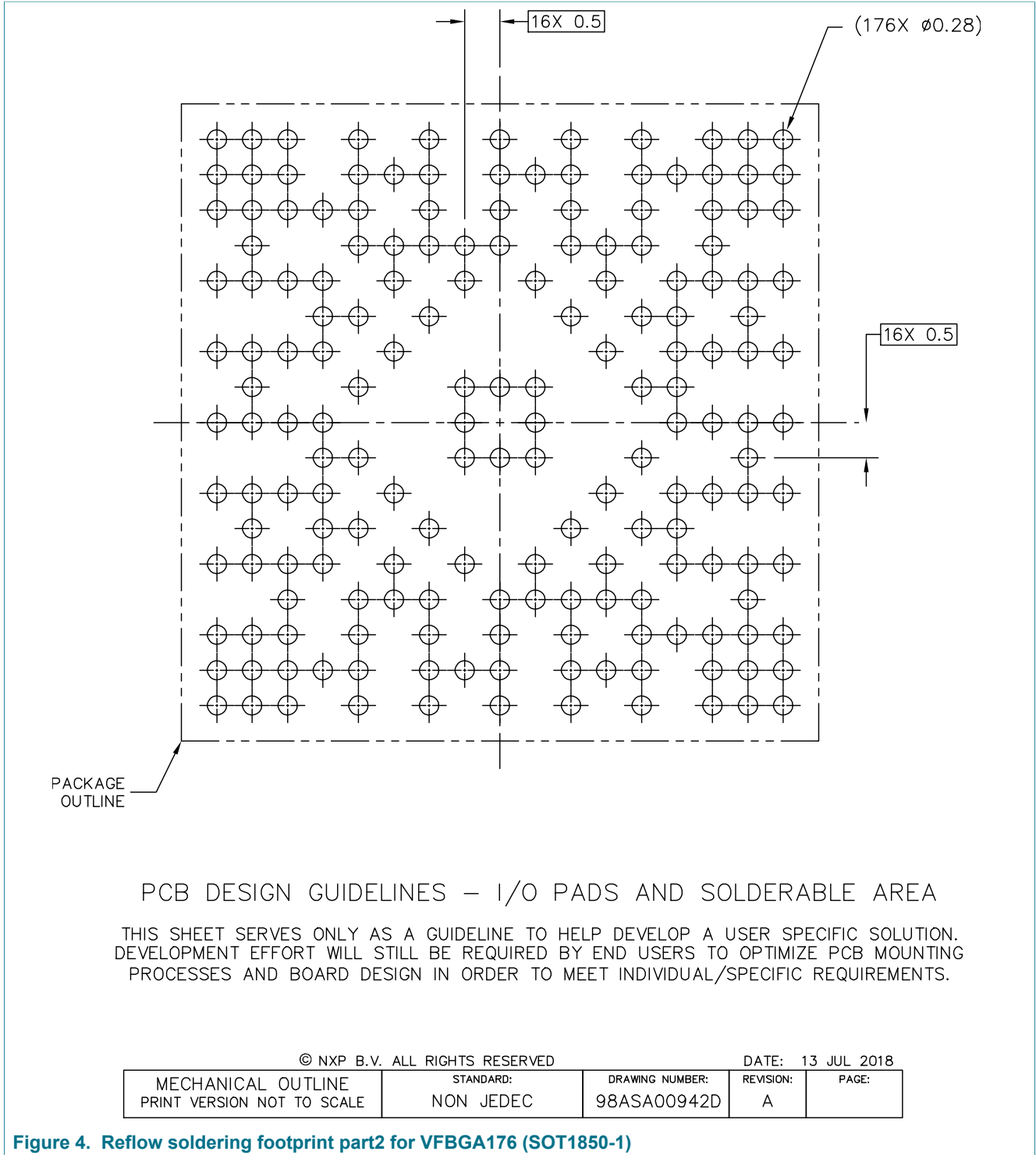


Figure 4. Reflow soldering footprint part2 for VFBGA176 (SOT1850-1)

VFBGA176, plastic, very thin fine-pitch ball grid array; 176 balls; 0.5 mm pitch; 9 mm x 9 mm x 0.86 mm body

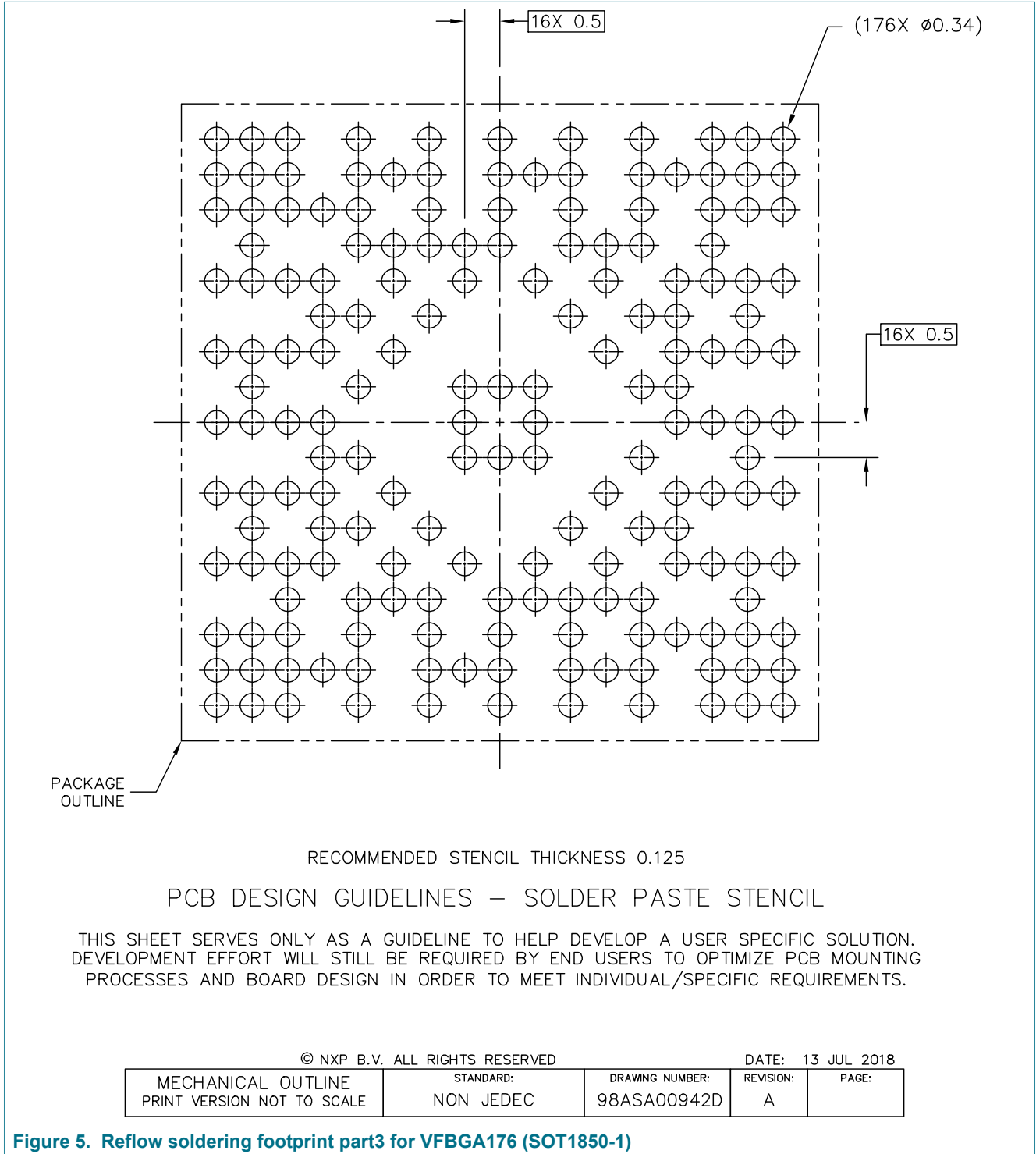


Figure 5. Reflow soldering footprint part3 for VFBGA176 (SOT1850-1)

## 4 Legal information

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